

AMENDMENTS TO THE CLAIMS

Listing Of Claims

Claims 1-56 (Canceled)

57. (currently amended) A semiconductor package comprising:

a leadframe;

a die on the leadframe; and

a plastic body comprising a first polymer member on the die or the leadframe, and a second polymer member encapsulating the first polymer member, the first polymer member ~~and~~ having a selected geometry configured to provide substantially equal volumes of the second polymer member on either side of the leadframe.

~~configured to adjust a selected characteristic of the package.~~

58. (currently amended) The semiconductor package of claim 57 wherein the first polymer member includes a filler configured to provide a selected characteristic of the package.

~~selected characteristic comprises a package bow.~~

60. (currently amended) The semiconductor package of claim 57 wherein the first polymer member includes a filler configured to provide an increased rigidity for the package.

~~selected characteristic comprises a package warpage.~~

61. (currently amended) The semiconductor package of claim 57 wherein the first polymer member comprises an epoxy resin.
~~a molded material.~~

62. (previously presented) The semiconductor package of claim 57 wherein the first polymer member comprises a tape material.

63. (previously presented) The semiconductor package of claim 57 wherein the first polymer member encapsulates the die.

64. (currently amended) The semiconductor package of claim 57 wherein the first polymer member and the second polymer member comprise a same molding compound.
~~are selected to provide a substantially equal volume of a molding compound on either side of the leadframe.~~

65. (currently amended) A semiconductor package comprising:

a leadframe;

a die on the leadframe;

a first polymer member on the die or the leadframe; and

a second polymer member encapsulating the first polymer member;

the first polymer member ~~and the second polymer member~~ having a selected geometries geometry and at least one filler configured to provide a selected characteristic for the package.

66. (currently amended) The semiconductor package of claim 65 wherein the selected ~~geometries~~ geometry provides substantially equal ~~comprise a volumes~~ of a molding compound of the second polymer member on either side of the leadframe.

67. (currently amended) The semiconductor package of claim 65 wherein the selected ~~geometries~~ geometry and the filler are configured to reduce a package bow.

68. (currently amended) The semiconductor package of claim 65 wherein the selected ~~geometries~~ geometry and the filler are configured to reduce a package warpage.

69. (currently amended) The semiconductor package of claim 65 wherein the first polymer member and the second polymer member comprises a same molding compound. ~~substantially encapsulating the die.~~

70. (currently amended) The semiconductor package of claim 65 wherein the first polymer member and the second polymer member comprise a same molded plastic.

71. (currently amended) A semiconductor package ~~having a parting line~~ comprising:

a leadframe having a first side and a second side;

a die on the leadframe;

a polymer member on the die or the leadframe; and

a plastic body comprising a molding compound encapsulating the polymer member and at least a portion of the leadframe, the plastic body having a first portion on

the first side having a first volume and a second portion on the second side having a second volume;

the polymer member configured to equalize the first volume and the second volume.

~~provide a substantially equal volume of the molding compound on either side of the parting line.~~

72. (previously presented) The semiconductor package of claim 71 wherein the polymer member comprises a material selected from the group consisting of epoxy, silicone, room temperature vulcanizing (RTV) and polyimide.

73. (previously presented) The semiconductor package of claim 71 wherein the polymer member comprises a tape material.

74. (previously presented) The semiconductor package of claim 71 wherein the polymer member encapsulates the die.

75. (previously presented) The semiconductor package of claim 71 wherein the leadframe has a lead-on-chip configuration.

76. (previously presented) The semiconductor package of claim 71 wherein the die is attached and wire bonded to the leadframe.

77. (previously presented) The semiconductor package of claim 71 wherein the polymer member comprises the molding compound.

78. (currently amended) A semiconductor package comprising:

a leadframe;

a die on the leadframe; and

a first polymer member on the die or the leadframe including a filler; and

a second polymer member on the first polymer member and the leadframe;

the first polymer member and the filler configured to provide a selected characteristic in the second polymer member.

79. (previously presented) The semiconductor package of claim 78 wherein the selected characteristic comprises increased rigidity.

80. (previously presented) The semiconductor package of claim 78 wherein the second polymer member comprises substantially equal volumes of a molding compound on either side of the leadframe.

81. (previously presented) The semiconductor package of claim 78 wherein the first polymer member substantially encapsulates the die.

82. (previously presented) The semiconductor package of claim 78 wherein the second polymer member substantially encapsulates the first polymer member.